



CED07N65B/CEU07N65B

N-Channel Enhancement Mode Field Effect Transistor

FEATURES

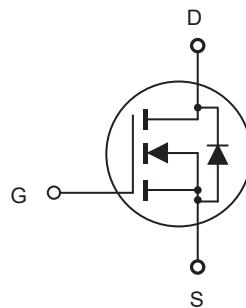
- 700V@ T_J max, 6A, $R_{DS(ON)} = 1.4\Omega$ @ $V_{GS} = 10V$.
- Super high dense cell design for extremely low $R_{DS(ON)}$.
- High power and current handing capability.
- Pb-free lead plating ; RoHS compliant.
- Halogen Free.
- TO-251 & TO-252 package.



CEU SERIES
TO-252(D-PAK)



CED SERIES
TO-251(I-PAK)



ABSOLUTE MAXIMUM RATINGS $T_C = 25^\circ C$ unless otherwise noted

| Parameter | Symbol | Limit | Units |
|--|----------------|------------|-------|
| Drain-Source Voltage | V_{DS} | 650 | V |
| Gate-Source Voltage | V_{GS} | ± 30 | V |
| Drain Current-Continuous @ $T_C = 25^\circ C$ @ $T_C = 100^\circ C$ | I_D | 6 | A |
| | | 4 | A |
| Drain Current-Pulsed ^a | I_{DM} | 24 | A |
| Maximum Power Dissipation @ $T_C = 25^\circ C$ - Derate above 25°C | P_D | 107 | W |
| | | 0.71 | W/°C |
| Single Pulsed Avalanche Energy ^d | E_{AS} | 121.5 | mJ |
| Single Pulsed Avalanche Current ^d | I_{AS} | 4.5 | A |
| Operating and Store Temperature Range | T_J, T_{stg} | -55 to 175 | °C |

Thermal Characteristics

| Parameter | Symbol | Limit | Units |
|---|-----------------|-------|-------|
| Thermal Resistance, Junction-to-Case | $R_{\theta JC}$ | 1.4 | °C/W |
| Thermal Resistance, Junction-to-Ambient | $R_{\theta JA}$ | 50 | °C/W |



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Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

| Parameter | Symbol | Test Condition | Min | Typ | Max | Units |
|--|----------------------------|---|-----|------|------|---------------|
| Off Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$ | 650 | | | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{\text{DS}} = 650\text{V}, V_{\text{GS}} = 0\text{V}$ | | | 1 | μA |
| Gate Body Leakage Current, Forward | I_{GSSF} | $V_{\text{GS}} = 30\text{V}, V_{\text{DS}} = 0\text{V}$ | | | 100 | nA |
| Gate Body Leakage Current, Reverse | I_{GSSR} | $V_{\text{GS}} = -30\text{V}, V_{\text{DS}} = 0\text{V}$ | | | -100 | nA |
| On Characteristics^b | | | | | | |
| Gate Threshold Voltage | $V_{\text{GS}(\text{th})}$ | $V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$ | 2 | | 4 | V |
| Static Drain-Source On-Resistance | $R_{\text{DS}(\text{on})}$ | $V_{\text{GS}} = 10\text{V}, I_D = 3.5\text{A}$ | | 1.15 | 1.4 | Ω |
| Dynamic Characteristics^c | | | | | | |
| Input Capacitance | C_{iss} | $V_{\text{DS}} = 25\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$ | | 1075 | | pF |
| Output Capacitance | C_{oss} | | | 120 | | pF |
| Reverse Transfer Capacitance | C_{rss} | | | 15 | | pF |
| Switching Characteristics^c | | | | | | |
| Turn-On Delay Time | $t_{\text{d}(\text{on})}$ | $V_{\text{DD}} = 300\text{V}, I_D = 6\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 25\Omega$ | | 32 | | ns |
| Turn-On Rise Time | t_r | | | 15 | | ns |
| Turn-Off Delay Time | $t_{\text{d}(\text{off})}$ | | | 67 | | ns |
| Turn-Off Fall Time | t_f | | | 21 | | ns |
| Total Gate Charge | Q_g | $V_{\text{DS}} = 480\text{V}, I_D = 1\text{A}, V_{\text{GS}} = 10\text{V}$ | | 23 | | nC |
| Gate-Source Charge | Q_{gs} | | | 5 | | nC |
| Gate-Drain Charge | Q_{gd} | | | 8 | | nC |
| Drain-Source Diode Characteristics and Maximum Ratings | | | | | | |
| Drain-Source Diode Forward Current | I_S | | | | 6 | A |
| Drain-Source Diode Forward Voltage ^b | V_{SD} | $V_{\text{GS}} = 0\text{V}, I_S = 3\text{A}$ | | | 1.5 | V |
| Notes : | | | | | | |
| a.Repetitive Rating : Pulse width limited by maximum junction temperature. | | | | | | |
| b.Pulse Test : Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$. | | | | | | |
| c.Guaranteed by design, not subject to production testing. | | | | | | |
| d.L =12mH, $I_{\text{AS}} = 4.5\text{A}$, $V_{\text{DD}} = 50\text{V}$, $R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$. | | | | | | |

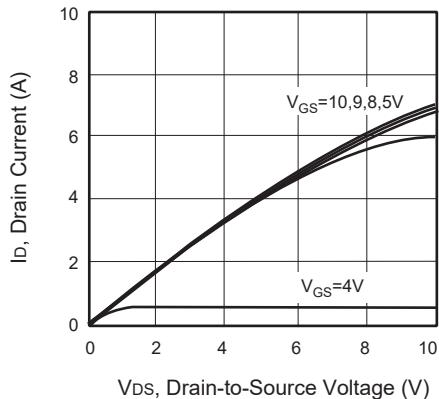


Figure 1. Output Characteristics

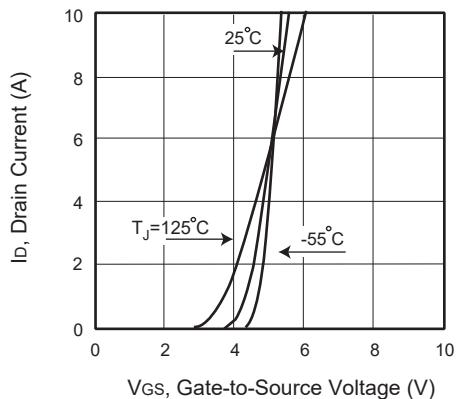


Figure 2. Transfer Characteristics

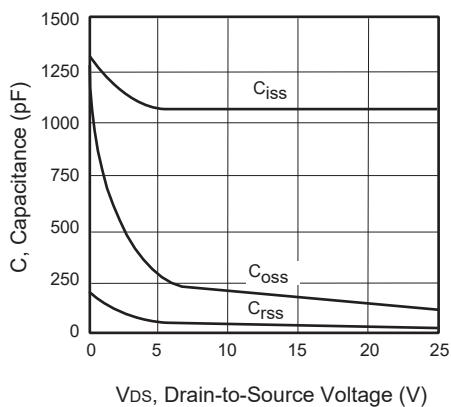


Figure 3. Capacitance

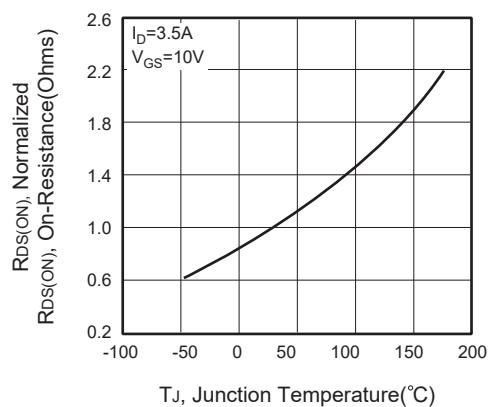


Figure 4. On-Resistance Variation with Temperature

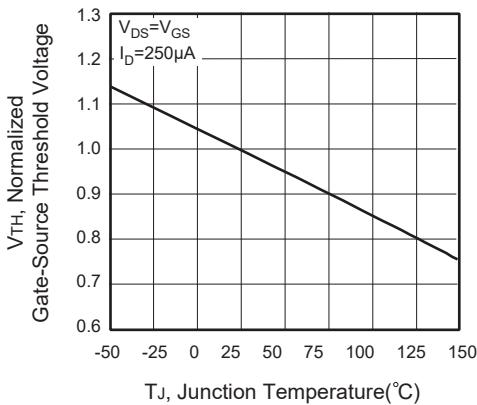


Figure 5. Gate Threshold Variation with Temperature

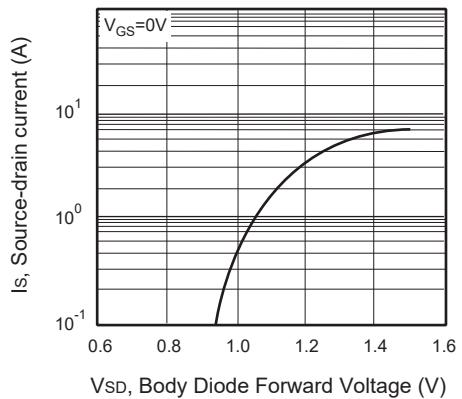


Figure 6. Body Diode Forward Voltage Variation with Source Current

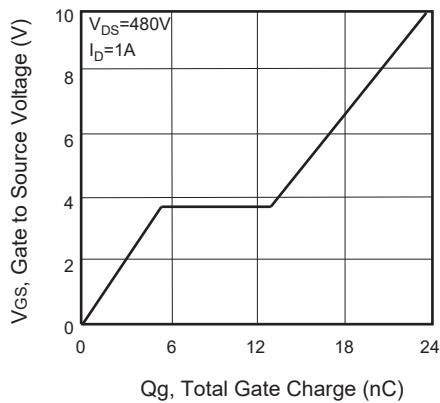
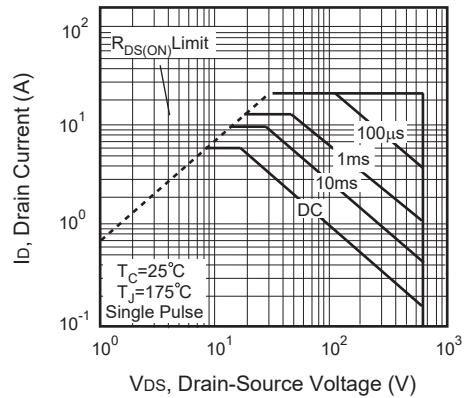
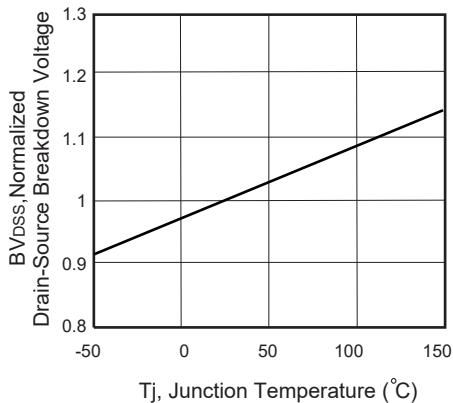


Figure 7. Gate Charge



**Figure 8. Maximum Safe
Operating Area**



**Figure 9. Breakdown Voltage Variation
VS Temperature**

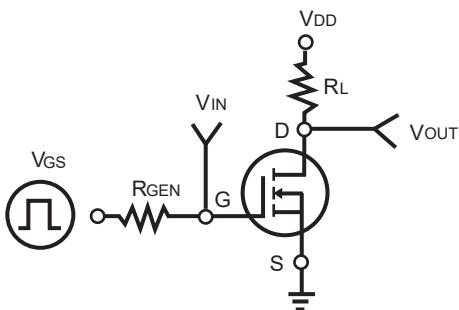


Figure 10. Switching Test Circuit

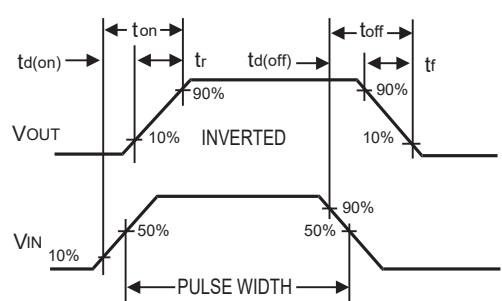


Figure 11. Switching Waveforms



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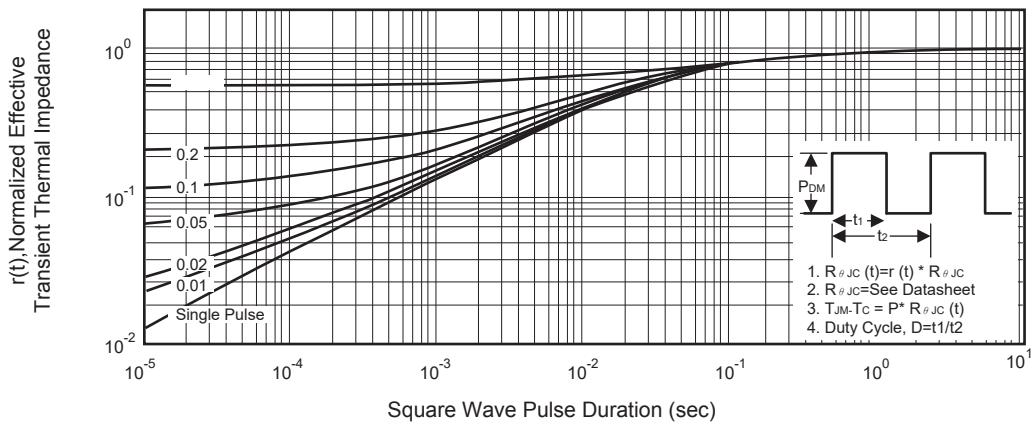


Figure 12. Normalized Thermal Transient Impedance Curve